221 Install label in silk-screened box after final wash. Text shall be 8 pt. type. Text shall be per the Label Table in the PDF schematic.
222 These assemblies are ESD sensitive, ESD precautions shall be observed.
223 These assemblies must be clean and free from flux and all components. Use of no-clean flux is not acceptable.
224 These assemblies must comply with workmanship standards EPC-4-610 Class 2, unless otherwise specified.
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANTS: Rev. A

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-00513</th>
<th>REV A</th>
<th>SUN REV: Not In VersionControl</th>
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<tr>
<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED: 3/15/2015 10:33:11 AM</td>
<td>TEXAS INSTRUMENTS</td>
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